

Serial No. 10/648,763

**IN THE CLAIMS:**

1. (Previously presented) An organic electronic device structure comprising:
  - a first portion comprising a substrate and an organic electronic device region disposed over the substrate;
  - a second portion comprising a cover and a getter region; and
  - a radiation-cured, pressure-sensitive adhesive layer disposed between said first and second portions and adhering said first and second portions to one another, said adhesive layer being disposed over the entire organic electronic device region and at least a portion of the substrate.
2. (Original) The organic electronic device structure of claim 1, wherein said organic electronic device region is an OLED device region and said organic electronic device structure is an OLED device structure.
3. (Original) The organic electronic device structure of claim 1, wherein said adhesive layer is in the form a continuous layer.
4. (Withdrawn) The organic electronic device structure of claim 1, wherein said adhesive layer comprises two or more distinct portions.
5. (Original) The organic electronic device structure of claim 1, wherein said device comprises a single getter region.
6. (Withdrawn) The organic electronic device structure of claim 1, wherein said device comprises a plurality of getter regions.
7. (Original) The organic electronic device structure of claim 1, wherein said getter region is provided on a surface of said cover.

Serial No. 10/648,763

8. (Withdrawn) The organic electronic device structure of claim 1, wherein said cover comprises a groove, and wherein said getter region is provided within said groove.
9. (Previously presented) The organic electronic device structure of claim 1, wherein said adhesive layer is an ultraviolet-radiation-cured, pressure-sensitive adhesive layer.
10. (Original) The organic electronic device structure of claim 1, wherein said adhesive layer displays low out-gassing of harmful species.
11. (Original) The organic electronic device structure of claim 1, further comprising a protective layer between said organic electronic device region and said adhesive layer
12. (Original) The organic electronic device structure of claim 11, wherein said protective layer comprises a material selected from a silicon oxide, a silicon nitride, a silicon oxynitride, a metal oxide, an organic compound and an organometallic compound.
13. (Withdrawn) The organic electronic device structure of claim 1, wherein said device structure comprises a plurality of organic electronic devices.
14. (Withdrawn) The organic electronic device structure of claim 1, wherein said substrate is selected from a metal substrate, a semiconductor substrate, a glass substrate, a ceramic substrate and a polymer substrate.
15. (Original) The organic electronic device structure of claim 1, wherein said substrate is a composite substrate layer comprises (a) a polymer substrate sub-layer and (b) at least two alternating pairs of high-density sub-layers and planarizing sub-layers, which high-density sub-layers may be the same or different from each other and which planarizing sub-layers may be the same or different from each other.

Serial No. 10/648,763

16. (Withdrawn) The organic electronic device structure of claim 1, wherein said cover is selected from a metal cover, a semiconductor cover, a glass cover, a ceramic cover and a polymer cover layer.

17. (Original) The organic electronic device structure of claim 1, wherein said cover is a composite material layer that comprises (a) a polymer substrate sub-layer and (b) at least two alternating pairs of high-density sub-layers and planarizing sub-layers, which high-density sub-layers may be the same or different from each other and which planarizing sub-layers may be the same or different from each other.

18. (Original) The organic electronic device structure of claim 1, wherein said getter region is attached to said cover via an adhesive region.

19. (Original) The organic electronic device structure of claim 2, wherein said OLED device structure is a top-emitting OLED device structure.

20. (Previously presented) An OLED device structure comprising:

a first portion comprising a substrate and an OLED device region disposed over the substrate;

a second portion comprising a cover and a getter region; and

a radiation-cured, pressure-sensitive adhesive layer disposed between said first and second portions and adhering said first and second portions to one another, said adhesive layer being disposed over the entire OLED device region and at least a portion of the substrate

wherein said OLED device structure is at most 0.4 mm in thickness.

21. (Original) The organic electronic device structure of claim 2, wherein said OLED device structure is a flexible device structure.

22. (Withdrawn) A method of making the organic electronic device structure of claim 1, comprising:

Serial No. 10/648,763

providing said first and second portions;

attaching said first portion to said second portion with said adhesive layer by application of pressure; and

exposing said adhesive layer to radiation.

23. (Withdrawn) The method of claim 22, wherein said radiation is ultraviolet radiation.

24. (Withdrawn) The method of claim 22, wherein said second portion is provided by a method comprising: providing said cover; and applying a film of getter material to said cover.

25. (Withdrawn) The method of claim 24, wherein said film of getter material further comprises an adhesive layer.

26. (Withdrawn) The method of claim 22, wherein said cover comprises a groove and wherein said second portion is provided by a method comprising: (a) providing said cover; (b) disposing a liquid getter within said groove; and (c) activating said liquid getter.

27. (Withdrawn) The method of claim 22, wherein said method is a web-based processing method.

28. (Withdrawn) The method of claim 22, wherein said first portion is adhered to said second portion by a method comprising: (a) providing an adhesive-primed portion comprising (i) said adhesive layer and (ii) one of said first and second portions; and (b) contacting said adhesive-primed portion with the other of said first and second portions.

29. (Withdrawn) The method of claim 28, wherein the adhesive layer is transferred from a release liner to one of the first and second portions to form said adhesive primed portion.

Serial No. 10/648,763

30. (Withdrawn) The method of claim 22, further comprising removing gas bubbles that are trapped (a) within the adhesive layer or (b) between said adhesive layer and either or both of the first and second portions.
31. (Withdrawn) The method of claim 30, wherein said bubbles are removed by the application of one or more of (a) heat, (b) pressure, and (c) vacuum.